
Bluetooth Module Datasheet

CZW-3034-02

Model: CZW-3034-02

Hardware Version: V2.0

Release Date: 2018.02.21

ShenZhen Cheng Zhi Wei Technology Co.,Ltd

Tel: (0755) 83328582

E-mail: xh@czwtech.com

Web: www.czwtech.com

Shenzhen

List of Contents

1 summary.....	3
2 General specifications.....	3
3 Key features.....	4
3.1 Device description.....	4
3.2 Features.....	4
3.3 Audio subsystem.....	4
3.4 Application subsystem.....	4
3.5 Bluetooth subsystem.....	5
3.6 Li-ion battery charger.....	5
3.7 Power management.....	5
4 Applications.....	5
5 Block diagram.....	6
6 Module package Information.....	7
6.1 Pinout diagram and package dimensions.....	7
6.2 Module Pin descriptions.....	8
7 Pin function description.....	9-11
8 Reference application circuit.....	12
9 Characteristics.....	13
9.1 Absolute Maximum Ratings.....	13
9.2 Recommended Operating Conditions.....	13
10 Recommended reflow temperature profile.....	13

1 summary

CZW-3034-02 is a Bluetooth module designed by ShenZhen Cheng Zhi Wei Technology Co.,Ltd. using Qualcomm Bluetooth chip qcc3034。

CZW-3034-02 is a Bluetooth, audio and programmable application processor. It includes high-performance, analog, and digital audio codecs, Class-AB and Class-D headphone drivers, advanced power management, Li-ion battery charger, light-emitting diode (LED) drivers, and flexible interfaces including inter integrated circuit sound (I² S), inter-integrated circuit interface (I² C), universal asynchronous receiver transmitter (UART), and programmable input/output (PIO)。

CZW-3034-02 package is compatible with czw02 series pins, easy replacement and upgrade

2 General specifications

Model Name	CZW-3034-02
Package	54 Pin Module
Dimension	13mm x 18mm x 2.4mm
Chipset	QCC3034
Bluetooth Version	Bluetooth 5.0
Power Class	Class2
Transmission Distance	≥10M
Voltage	2.8~4.2V
Temperature	-10~+70℃
Storage Temperature	-40~+85℃
Frequency Range	2402~2480MHz
Maximum RF Transmit Power	9dBm
π/4 DQPSK Receive Sensitivity	-91dBm
8DPSK Receive Sensitivity	-81dBm

3 Key Features

3.1 Device description

- ★ High-performance programmable Bluetooth® stereo audio SoC with Qualcomm® aptX™ audio
- ★ Fully qualified single-chip dual-mode Bluetooth v5.0 system
- ★ Tri-core processor architecture with low power for extended battery life

3.2 Features

- ★ Qualified to Bluetooth® v5.0 specification
- ★ 120 MHz Qualcomm®Kalimba™ audio DSP
- ★ 32 MHz Developer Processor for applications
- ★ Firmware Processor for system
- ★ Flexible QSPI flash programmable platform
- ★ Advanced audio algorithms
- ★ High-performance 24- bit stereo audio interface
- ★ Digital and analog microphone interfaces
- ★ Flexible PIO controller and LED pins with PWM support 1 or 2-mic Qualcomm® cVc™ headset noise reduction and echo cancellation technology
- ★ aptX, aptX HD, aptX Low Latency, SBC, and AAC audio codecs support
- ★ Serial interfaces: UART, Bit Serializer (I² C/SPI), USB 2.0
- ★ Integrated PMU: Dual SMPS for system/digital circuits, Integrated Li-ion battery charger

3.3 Audio subsystem

- ★ 32- bit Kalimba audio digital signal processor (DSP) core with flexible clocking from 2 MHz to 120 MHz to allow optimization and trade-off performance vs. power consumption
- ★ DSP runs from ROM
- ★ 80 KB program random access memory (RAM)
- ★ 256 KB data RAM
- ★ 5 Mb ROM

3.4 Application subsystem

- ★ Dual core application subsystem 32 MHz operation
- ★ 32- bit Firmware Processor
- ★ 32- bit Developer Processor
- ★ Both cores execute code from external flash memory using QSPI clocked at 32 MHz
- ★ On-chip caches per core allow for optimized performance and power consumption

3.5 Bluetooth subsystem

- ★ Qualified to Bluetooth v5.0 specification including 2 Mbps Bluetooth low energy (Production parts)
- ★ Single ended antenna connection with on-chip balun and Tx/Rx switch
- ★ Bluetooth, Bluetooth low energy, and mixed topologies supported
- ★ Class 1 support

3.6 Li-ion battery charger

- ★ Integrated battery charger supporting internal mode (up to 200 mA) and external mode (up to 1.8 A)
- ★ Variable float (or termination) voltage adjustable in 50 mV steps from 3.65 V to 4.4 V
- ★ Thermal monitoring and management are implementable in application software
- ★ Pre-charge to fast charge transition configurable at 2.5 V, 2.9 V, 3.0 V, and 3.1 V

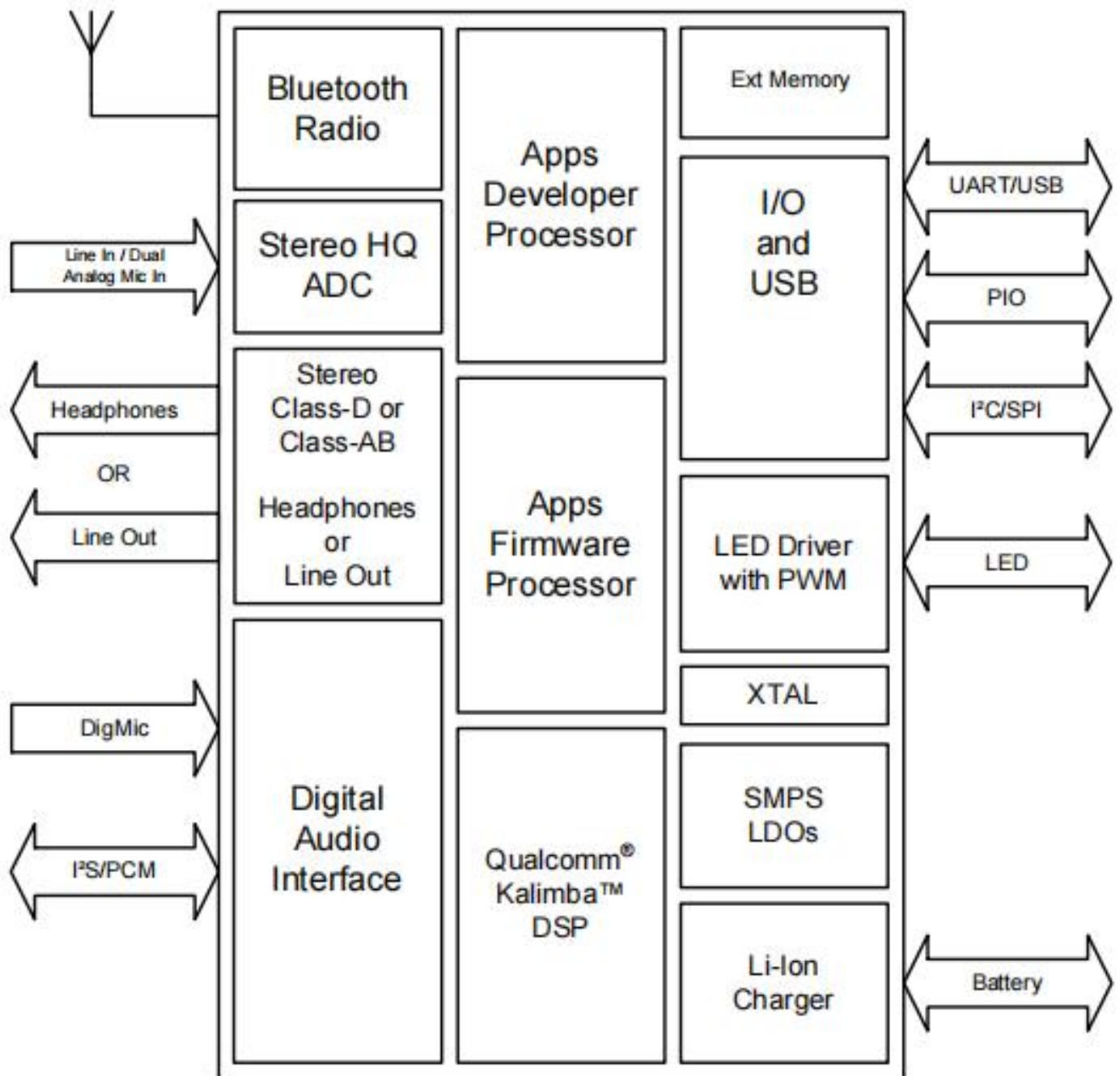
3.7 Power management

- ★ Integrated power management unit (PMU) to minimize external components
- ★ Runs directly from a Li-ion, USB, or external supply (2.8 V to 6.5 V)
- ★ Auto-switching between battery and USB (or other) charging source
- ★ Power islands employed to optimize power consumption for variety of use-cases
- ★ Dual switch-mode power supply (SMPS)

4 Applications

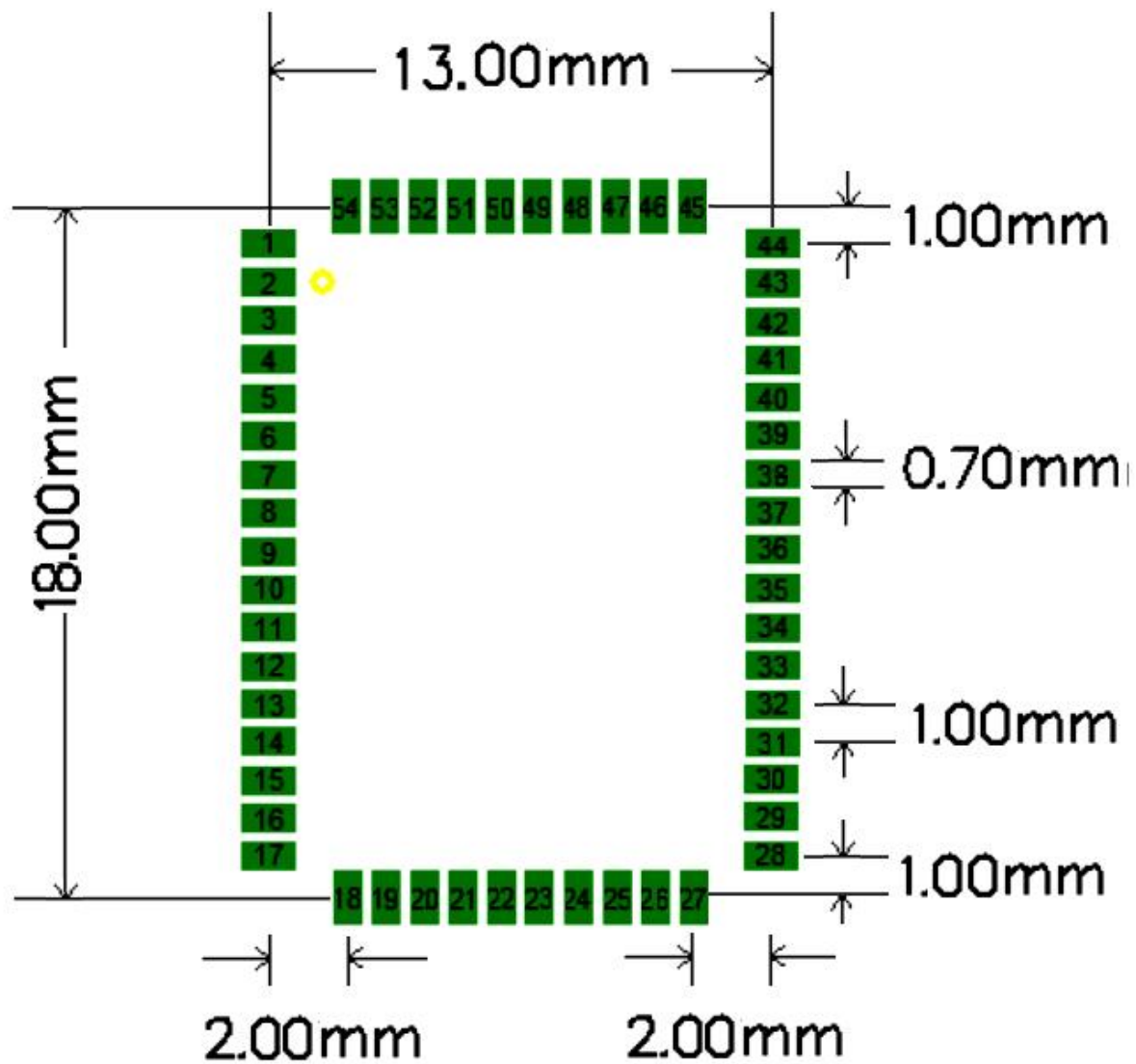
- ★ Wired/wireless stereo headsets/headphones
- ★ Qualcomm TrueWireless™ stereo earbuds

5 Block Diagram



6 Module Package Information

6.1 Pinout Diagram and package dimensions



LED2	18	PI020	54
LED4	19	PI021	53
LED5	20	PI061	52
GDN	21	PI060	51
1V8	22	PI052	50
VDD_PADS1	23	PI053	49
VDD_PADS37	24	PI054	48
PI004	25	GDN	47
PI003	26	BT_RF	46
PI006	27	GDN	45

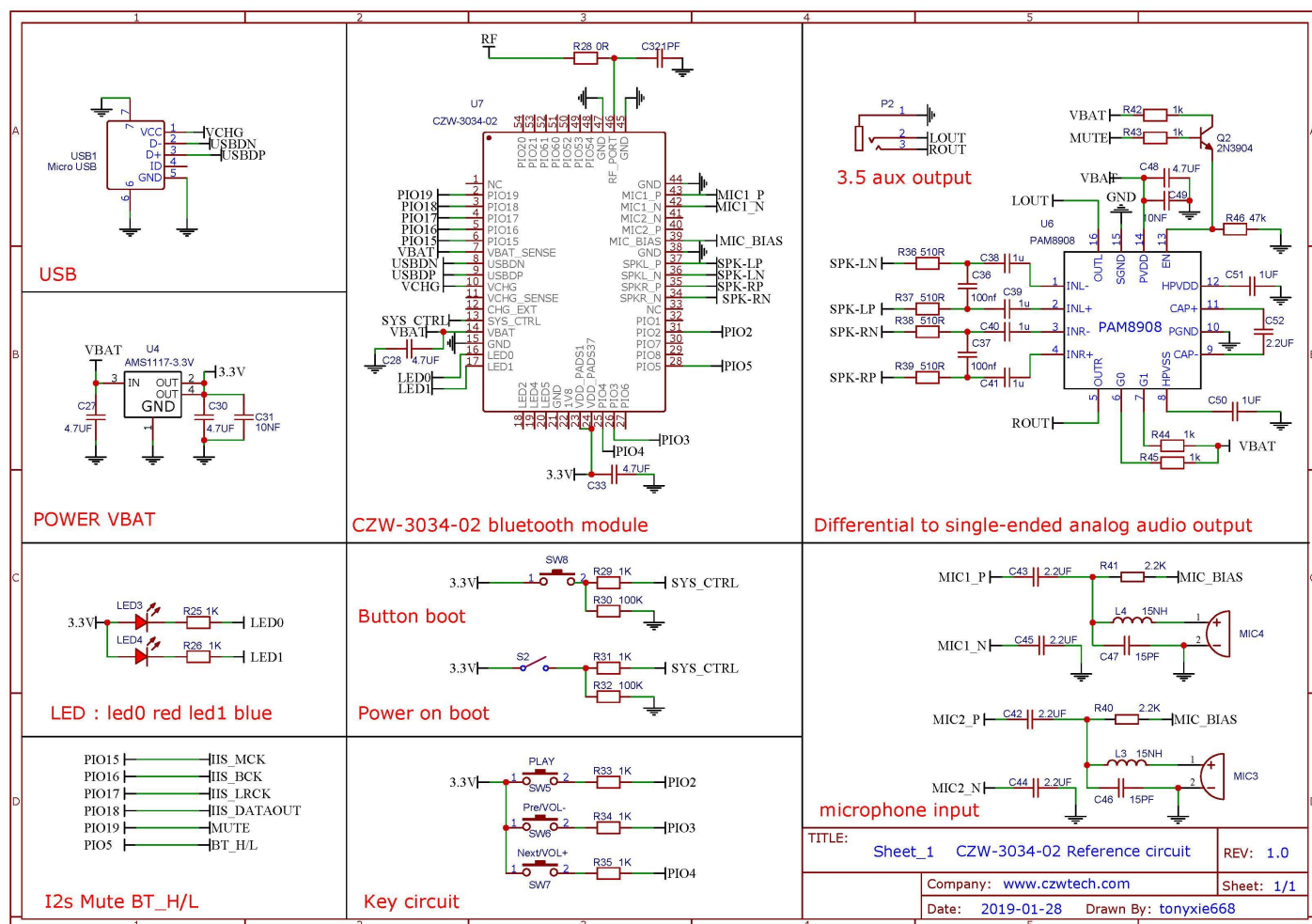
7 Pin Function Description

Pin#	Pin Name	Pin type	Description
1	NC	NC	NC
2	PIO[19]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 19. Alternative function: PCM_DIN[0]
3	PIO[18]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 18. Alternative function: PCM_DOUT[0]
4	PIO[17]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 17. Alternative function: PCM_SYNC
5	PIO[16]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 16. Alternative function: PCM_CLK
6	PIO[15]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 15. Alternative function: MCLK_OUT
7	VBAT_SENSE	Analog	Battery voltage sense input.
8	USB_DN	Digital	USB Full Speed device D- I/O. IEC-61000-4-2 (device level) ESD Protection
9	USB_DP	Digital	USB Full Speed device D+ I/O. IEC-61000-4-2 (device level) ESD Protection
10	VCHG	Supply	Charger input to Bypass regulator.
11	VCHG_SENSE	Analog	Charger input sense pin after external mode sense-resistor. High impedance. NOTE If using internal charger or no charger, connect VCHG_SENSE direct to VCHG.
12	CHG_EXT	Analog	External charger transistor current control. Connect to base of external charger transistor as per application schematic.
13	SYS_CTRL	Digital input	Typically connected to an ON/OFF push button. Boots device in response to a button press when power is still present from battery and/or charger but software has placed the device in the OFF or DORMANT state. Additionally useable as a digital input in normal operation. No pull. Additional function: PIO[0] input only
14	VBAT	Supply	Battery voltage input.
15	GND	Ground	Ground
16	LED[0]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
17	LED[1]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.

Pin#	Pin Name	Pin type	Description
18	LED[2]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
19	LED[4]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
20	LED[5]	Analog or digital input/ open drain output.	General-purpose analog/digital input or open drain LED output.
21	GND	Ground	Ground
22	1V8	Supply	1.8V voltage output
23	VDD_PADS_1	Supply	1.8 V/3.3 V PIO supply.
24	VDD_PADS_3、7	Supply	1.8 V/3.3 V PIO supply.
25	PIO[4]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 4. Alternative function: TBR_MOSI[1]
26	PIO[3]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 3. Alternative function: TBR_MISO[2]
27	PIO[6]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 6. Alternative function: TBR_MOSI[0]
28	PIO[5]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 5. Alternative function: TBR_MISO[1]
29	PIO[8]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 8. Alternative function: TBR_CLK
30	PIO[7]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 7. Alternative function: TBR_MISO[0]
31	PIO[2]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 2. Alternative function: TBR_MISO[3]
32	PIO[1]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Automatically defaults to RESET# mode when the device is unpowered, or in off modes. Reconfigurable as a PIO after boot. Alternative function: Programmable I/O line 1
33	NC	NC	NC
34	SPKR_N	VDD_AUDIO_HP_SPKR	Headphone/speaker differential right output, negative. Alternative function: Differential right line output, negative
35	SPKR_P	VDD_AUDIO_HP_SPKR	Headphone/speaker differential right output, positive. Alternative function: Differential right line output, positive
36	SPKL_N	VDD_AUDIO_HP_SPKL	Headphone/speaker differential left output, negative. Alternative function: Differential left line output, negative

Pin#	Pin Name	Pin type	Description
37	SPKL_P	VDD_AUDIO_HP_SPKL	Headphone/speaker differential left output, positive. Alternative function: Differential left line output, positive
38	GND	Ground	Ground
39	MIC_BIAS	VDD_AUDIO_1V8	Mic bias output.
40	MIC2_N	VDD_AUDIO_1V8	Microphone differential 2 input, negative. Alternative function: Differential audio line input right, negative
41	MIC2_P	VDD_AUDIO_1V8	Microphone differential 2 input, positive. Alternative function: Differential audio line input right, positive
42	MIC1_N	VDD_AUDIO_1V8	Microphone differential 1 input, negative. Alternative function: Differential audio line input left, negative
43	MIC1_P	VDD_AUDIO_1V8	Microphone differential 1 input, positive. Alternative function: Differential audio line input left, positive
44	GND	Ground	Ground
45	GND	Ground	Ground
46	BT_RF	VDD_BT_RADIO	Bluetooth transmit/receive.
47	GND	Ground	Ground
48	PIO[54]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 54. Alternative function: SDIO_D[0]
49	PIO[53]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 53. Alternative function: SDIO_CMD
50	PIO[52]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 52. Alternative function: SDIO_CLK
51	PIO[60]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 60.
52	PIO[61]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 61.
53	PIO[21]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 21. Alternative function: PCM_DOUT[2]
54	PIO[20]	Digital: Bidirectional with programmable strength internal pull- up/pull-down	Programmable I/O line 20. Alternative function: PCM_DOUT[1]

8 Reference application circuit



Notice: for reference only, please design the circuit according to the actual application

9 Electrical Characteristics

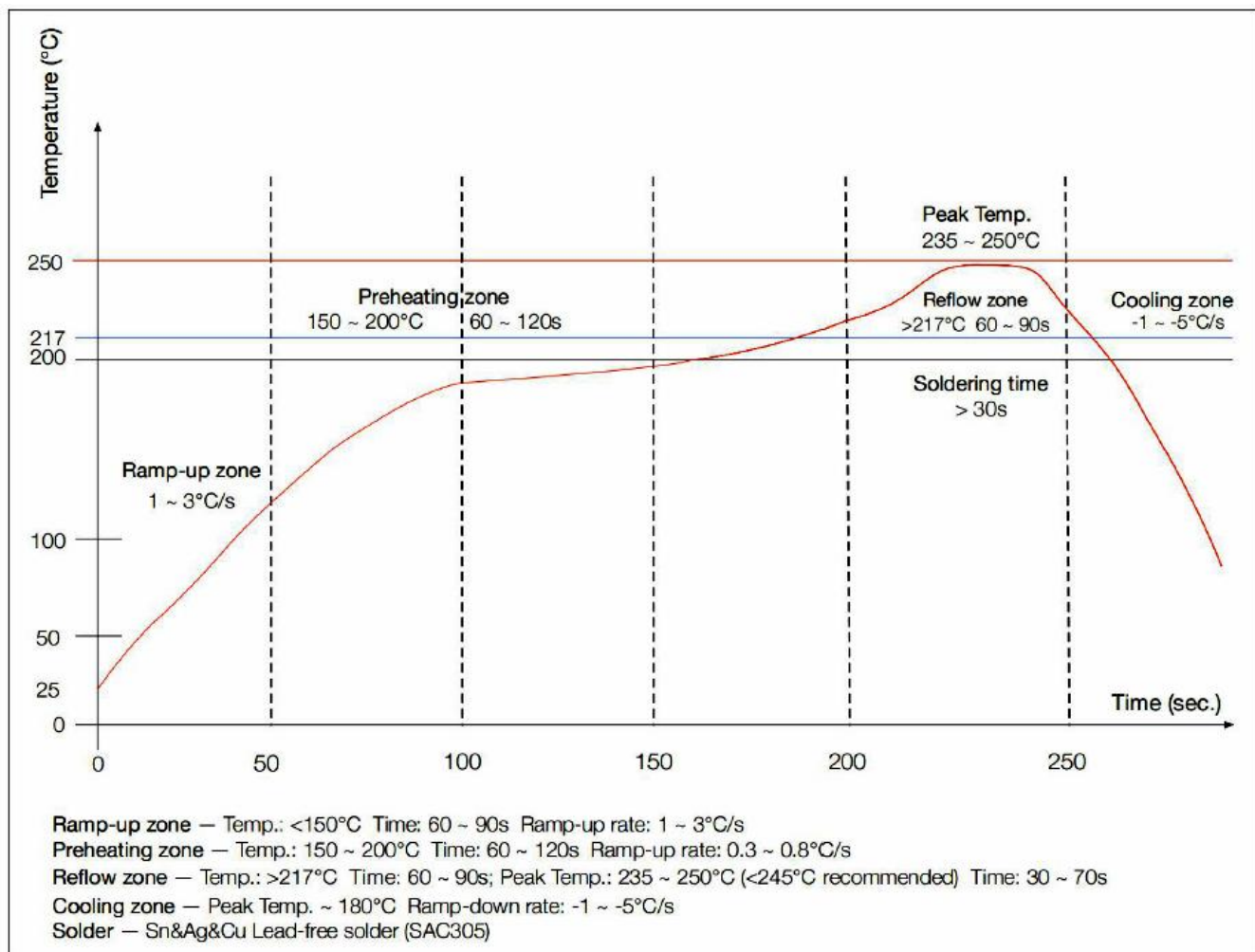
9.1 Absolute Maximum Ratings

Rating	Minimum	Maximum
Storage temperature	-40°C	+85°C

9.2 Recommended Operating Conditions

Operating Condition	Minimum	Maximum
Operating temperature range	-40°C	+85°C
Supply voltage: VBAT	+2.8V	+4.3V

10 Recommended reflow temperature profile



The module Must go through 100°C baking for at least 12 hours before SMT AND IR reflow process!

IMPORTANT NOTICE

ShenZhen Cheng Zhi Wei Technology Co.,Ltd (CZW) reserve the right to make changes to their products or to discontinue any product or service without notice, and advise customers to obtain the latest version of relevant information to verify, before placing orders, that information being relied on is current. All products are sold subject to the CZW terms and conditions of sale supplied at the time of order acknowledgement, including those pertaining to warranty, patent infringement, and limitation of liability.

CZW warrants performance of its products to specifications applicable at the time of sale in accordance with CZW's standard warranty. Testing and other quality control techniques are utilized to the extent CZW deems necessary to support this warranty. Specific testing of all parameters of each device is not necessarily performed, except those mandated by government requirements.

In order to minimize risks associated with customer applications, adequate design and operating safeguards must be used by the customer to minimize inherent or procedural hazards. CZW products are not authorized for use as critical components in life support devices or systems without the express written approval of an officer of the company. Life support devices or systems are devices or systems that are intended for surgical implant into the body, or support or sustain life, and whose failure to perform when properly used in accordance with instructions for use provided, can be reasonably expected to result in a significant injury to the user. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

CZW assumes no liability for applications assistance or customer product design. CZW does not warrant or represent that any license, either express or implied, is granted under any patent right, mask work right, or other intellectual property right of CZW covering or relating or any combination, machine, or process in which such products or services might be or are used.